

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hideo Okamoto</td> <td>02/21/2008</td> </tr> <tr> <td>Noritoshi Eguchi</td> <td>03/11/2008</td> </tr> </tbody> </table>		Name	Execution Date	Hideo Okamoto	02/21/2008	Noritoshi Eguchi	03/11/2008
Name	Execution Date						
Hideo Okamoto	02/21/2008						
Noritoshi Eguchi	03/11/2008						
RECEIVING PARTY DATA							
Name:	Sony Corporation						
Street Address:	1-7-1 Konan, Minato-ku						
City:	Tokyo 108-0075						
State/Country:	JAPAN						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12099939</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12099939		
Property Type	Number						
Application Number:	12099939						
CORRESPONDENCE DATA							
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
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ATTORNEY DOCKET NUMBER:	09792909-7251						
NAME OF SUBMITTER:	David R. Metzger						
Total Attachments: 2 source=Sony_7251_Assgmt1#page1.tif source=Sony_7251_Assgmt1#page2.tif							

OP \$40.00 12099939

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in MOUNTING STRUCTURE FOR PLURALITY OF LENSES, CAMERA MODULE, AND ELECTRONIC EQUIPMENT

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 12/099,939, Filing Date: April 9, 2008.

This assignment executed on the dates indicated below.

<u>Hideo OKAMOTO</u>	_____
Name of first or sole inventor	Execution date of U.S. Patent Application
<u>Chiba, Japan</u>	_____
Residence of first or sole inventor	_____
<u>岡本秀男</u>	<u>21/2/2008</u>
Signature of first or sole inventor	Date of this assignment

Nobuyuki ADACHI

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Noritoshi EGUCHI

Name of third inventor

Execution date of U.S. Patent Application

Saitama, Japan

Residence of third inventor

三井 典稔

11/3/2008

Signature of third inventor

Date of this assignment

Name of fourth inventor

Execution date of U.S. Patent Application

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Name of fifth inventor

Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment